

KUN SHAN UNIVERSITY - 2027 Spring Program

—Admission Brochure—

Semiconductor Intelligent Operation and Maintenance Program 專班名稱: 半導體智慧維運專班	
Degree 學位	2-Year Post-Baccalaureate Degree/學士後二年制學士專班
College 學院	College of Engineering/工程學院
Department 學系	Department of Electrical Engineering /電機工程系
Begin Term 開始學期	2027 Spring Semester (Enroll in February) /春季(2027 年 2 月入學)
Introduction Language 授課語言	Course taught in English/英文授課
Nationality of admission 招生國籍	Philippines/菲律賓
Language Proficiency 語言能力	English Proficiency Requirement - Applicants must provide proof of English proficiency equivalent to TOEIC 550, CEFR B1, or above. However, applicants from countries where English is officially recognized by the Ministry of Foreign Affairs of the Republic of China (Taiwan) (e.g., the Philippines) are exempt from submitting English proficiency test scores. Chinese Proficiency Requirement - Language Proficiency Requirements After Enrollment: Both Listening and Reading at least at level A2 before the second academic year. 英語能力要求 - 申請入學之英語能力須達 TOEIC 550 分或 CEFR B1 級(含)以上。但來自中華民國(台灣)外交部認定英語為官方語言之國家名單者(如菲律賓),得免附英語能力檢定證明。 中文能力要求 - 入學後第 2 年開始前華語文能力測驗(TOCFL)聽、讀 2 項皆達 A2 級(含)以上
Application Documents 申請文件	- Application form - The highest-level degree diploma - The highest degree's full transcript of records - Proof of English Proficiency (TOEIC 550 or above, or equivalent CEFR B1). - Statement of purpose - Passport (if available)

	7. Other supporting documents for review. (e.g., classroom performance and academic achievements in free Chinese preparatory courses at overseas bases or stations, autobiographies in Chinese or English, certificates, awards, etc.). 1. 入學申請表 2. 最高學歷證明 3. 最高學歷之歷年成績單 4. 語文能力證明(多益 550 分或相當於 CEFR B1 等級以上之英文能力證明) 5. 目的聲明書 6. 護照(如果有) 7. 其他有利之審查資料。(如：參加海外基地或據點免費華語先修課程之課堂表現及學習成績、中文或英文自傳、證照、獎狀...等)
Interview/ Oral Exam 面試/口試	Interview with Collaborating Companies 面試(與合作企業)
Obligations/ Notes 義務規定/ 注意事項	<u>Obligations</u> 1. Students receiving industry-academia scholarships from the National Development Fund, Taiwan are obligated to stay and work in Taiwan for a corresponding period based on the number of years they received the scholarship. 2. Those receiving a one-year industry-academia scholarship have a one-year obligation to stay and work in Taiwan, while those receiving a two-year industry-academia scholarship have a two-year obligation to stay and work in Taiwan. ***Notes 1. If a student withdraws from the program midway during the academic term due to personal reasons, such as applying for transfer to another program, changing majors, taking a leave of absence, or returning to their home country, and after counseling from the school, still decides to give up continuing in the program, or if the school, in accordance with its regulations, decides to withdraw or expel the student, the student is required to fully repay any industry-academia scholarship funds received. 2. If a student chooses not to work for the collaborating company or in a related industry field after graduation, and despite counseling from the school, the student is required to fully repay any industry-academia scholarship funds received. 3. If a student, after graduating and entering employment, violates company regulations leading to the lawful termination of the employment contract, and despite counseling from the school, the student should repay the industry-academia scholarship funds proportionally based on the number of months not employed; for a period less than one month, it will be counted as one month. 4. During the period of fulfilling the employment obligation after graduation, students are required to work in a position within domestic collaborating companies in Taiwan. They are not allowed to be dispatched to work at overseas branches or be employed by overseas Taiwanese-owned companies. If a student fails to comply with the requirement of domestic employment, they should repay the industry-academia scholarship funds proportionally based on the number of months not employed in Taiwan; for a period less than one month, it will be counted as one month.

義務規定

1. 凡領取國家發展基金產學獎助金之學生，應依實際受領獎助年限，履行相對應期間之留臺工作義務。
2. 領取一年期產學獎助金者，畢業後應留臺工作一年；領取二年期產學獎助金者，畢業後應留臺工作二年。

注意事項

1. 學生於修業期間因個人因素中途退出本專班（包括申請轉系、轉學、休學、返國等），經學校輔導後仍決定放棄繼續就讀，或依校方相關規定遭退學或開除學籍者，應全額返還已領取之產學獎學金款項。
2. 學生畢業後未依規定至合作企業或相關產業領域就業，經學校輔導仍未履行就業義務者，應全額繳還已領取之產學獎助金。
3. 學生畢業後就業期間，如因違反公司規定致合法終止勞動契約，經學校輔導後，應依未履行就業義務之剩餘月份比例繳還產學獎助金；未滿一個月者，以一個月計算。
4. 學生於履行畢業後就業義務期間，應受僱於我國境內之合作企業從事相關職務，不得派駐海外分公司或任職於海外臺資企業；未依規定於國內就業者，應按未履行期間比例繳還產學獎助金，未滿一個月者，以一個月計算。

Scholarship 獎助學金

1. Tuition & Fees Subsidy:

- (1) Year 1: NT\$100,000
- (2) Year 2: NT\$100,000 (*Subject to passing TOCFL A2 Listening & Reading, plus university & partner enterprise evaluations*)

2. Administrative Fee & One-way Airfare:

- (1) The administrative fees have a maximum limit of NT\$10,000.
- (2) The one-way airfare is based on the most direct economy class flight to Taiwan. (Reimbursed with a maximum limit of NT\$9,000)

3. Enterprise Living Allowance / Internship Allowance:

- (1) Year 1: Monthly living allowance of NT\$10,000.
- (2) Year 2 (Internship Period): Monthly internship allowance of **NT\$33,000**.

1. 學雜費補助

- (1) 第一學年補助新臺幣 10 萬元整。
- (2) 第二學年補助新臺幣 10 萬元整；惟須通過華語文能力測驗(聽力與閱讀)A2 級(含)以上，並通過學校及合作企業之學業與實習表現審查，始得核發。

2. 行政費及機票補助

- (1) 行政費補助以新臺幣 1 萬元為上限。
- (2) 來臺單程機票補助以最直接航線之經濟艙票價為準，補助上限為新臺幣 9,000 元，採實報實銷方式辦理。

3. 企業生活津貼/實習津貼

- (1) 學生於修業期間(第 1 年)，合作企業每月提供生活津貼新臺幣 10,000 元。
- (2) 學生於第 2 年實習期間，合作企業每月提供實習津貼新臺幣 **33,000 元**。

Introduction
of the
Program
本專班介紹
及專班特色

This program is established in response to the demand of partner enterprises for highly skilled professionals in the operation and maintenance of semiconductor packaging and testing systems. It also aims to strengthen domestic talent cultivation and workforce development by actively expanding the recruitment of Filipino international students and attracting outstanding international talents to pursue higher education in Taiwan. Through an industry-academia collaborative training model that integrates university-based professional education with enterprise practical training, the program encourages students to remain employed by partner enterprises after graduation and engage in semiconductor-related technical careers, thereby supporting Taiwan's population policy, talent cultivation strategies, and industrial development planning.

In response to the growing demand for professional talent driven by industrial transformation, smart manufacturing development, technological advancement, and the rapid growth of the semiconductor industry, this program adopts an industry-oriented talent cultivation approach based on enterprise workforce requirements. Partner enterprises will participate throughout the entire training process, including student recruitment and selection, curriculum planning and instruction, off-campus internships, and career development. Through close industry-academia collaboration, the program enhances students' professional capabilities in semiconductor engineering technologies, packaging and testing equipment operation and maintenance, automation control, and practical industrial applications.

The program aims to cultivate internationally oriented technical professionals with professional knowledge, engineering skills, and hands-on capabilities in the field of semiconductor packaging and testing. By expanding the capacity for semiconductor talent cultivation and establishing a close collaboration mechanism between universities and enterprises, the program seeks to achieve the goals of joint talent development, talent retention within partner enterprises, and enhancement of Taiwan's semiconductor industry competitiveness.

本專班因應合作企業對於半導體封裝測試系統運轉與維護高階技術人才之需求，並配合強化國內產業人才培育與人力結構調整，積極擴大招收菲律賓籍國際學生，吸引優秀國際人才來臺就學。透過產學合作培育模式，結合學校專業教育與企業實務訓練，鼓勵學生於完成學業後留任合作企業發展，投入半導體產業相關技術工作，以呼應我國人口政策、人才培育策略及產業發展布局。

面對國內產業永續轉型、智慧製造推動、技術升級及半導體產業快速發展所衍生之專業人才需求，本專班以企業用人需求為核心，規劃符合產業實務導向之人才培育機制。合作企業將全程參與專班之招生選才、課程規劃與教學、校外實習及職涯發展等培育階段，透過產學雙向合作，強化學生於半導體工程技術、封裝測試設備操作與維護、自動化及產業實務應用等面向之專業能力。

本專班旨在培育具備半導體封裝測試領域專業知識、工程技術與實務操作能力之國際化技術人才，擴大半導體產業人才培育量能，並透過學校與企業之合作機制，達成共同培育人才、企業留用人才及提升臺灣半導體產業競爭力之目標。

This English-taught program is designed to cultivate professionals with expertise in the operation and maintenance of semiconductor packaging and testing systems. The curriculum emphasizes the integration of interdisciplinary knowledge with hands-on practical training through industry internships, thereby narrowing the gap between academic learning and industrial practice. The program covers professional subjects including semiconductor engineering technology, electrical engineering practice, automation and control, and mechatronic integration. It aims to provide industry with highly qualified technical personnel while developing future engineering and management professionals for partner enterprises.

(I) Graduation Requirements

1. Graduation Credits:

A total of 56 credits are required for graduation, including 38 required credits (comprising 18 credits of off-campus internship, 8 credits of professional required courses, and 12 credits of Chinese language courses) and 18 elective credits.

2. Program Duration:

The program is completed over two years, consisting of one year of on-campus coursework followed by one year of off-campus internship.

(II) Curriculum Planning

The Chinese language curriculum is designed to develop students' practical Chinese communication skills. The courses incorporate both everyday Chinese and workplace Chinese, enabling students to enhance their cross-cultural communication skills and practical language proficiency for both daily life and professional environments.

The professional curriculum includes courses such as Basic Electrical Engineering and Laboratory, Electronics and Laboratory, Semiconductor Industry Technology, Introduction to Automation, Programmable Logic Controller (PLC) Laboratory, Mechatronics Practice, Industrial Wiring Practice, Special Topics Research, and Workplace Practice and Experience Sharing. Through collaboration with partner enterprises in off-campus internship programs, the curriculum aims to bridge the gap between academic learning and industrial practice, while enhancing students' hands-on capabilities in semiconductor packaging and testing technologies as well as electrical engineering applications.

本專班為全英語授課，旨在培育學生具備在半導體封裝測試領域中運轉與維護工程與技術的專業能力。本學程著重於跨領域知識及實務的整合，配合企業之實習，以縮短學用之差距。課程內容包括半導體工程技術、電機實務、自動化控制及機電整合等專業技術。提供合乎企業需求之優質人力，且為合作企業儲備工程技術及管理人才。

(一) 專班之畢業應修學分數

1. 畢業學分數：共 56 學分，含必修 38 學分(其中校外實習 18 學分，專業課程 8 學分，華語課程 12 學分)、選修 18 學分。
2. 修業年限(2 年：含校內課程 1 年、校外實習 1 年)

(二) 課程規劃

華語課程以培養專班學生之實用華語溝通能力為目標；課程內容兼顧生活華語與職場華語需求，強化學生跨文化溝通與實務運用能力。

專業課程包含：基礎電學及實習、電子學及實習、半導體產業技術，自動化概論，可程式控制器實習，機電整合實務，工業配線實務，專題研究，職場實務分享等課程，並且藉由配合企業之校外實習，以縮短學用之差距，加強學生在半導體封裝與測試技術與電機工程的操作實務能力。

未來的願景 Future map	Employment career: Students should work in Taiwan after graduation for at least 2 years in the partnering enterprise. 本專班畢業生需進入合作企業在台工作至少兩年。 *** Collaborating Company 合作企業: 南茂科技股份有限公司(25 個職位) ChipMOS TECHNOLOGIES INC. (25 positions) Website : https://www.chipmos.com/index-en.aspx ■ Job Opportunities: Semiconductor Operations and Maintenance Engineers (25 Positions) ■ 職務需求：半導體維運工程師/ 25 人 Role Responsibilities: • Operation and Maintenance of Semiconductor Packaging and Testing Systems • Production Yield Management • Technical Documentation Development • Production Scheduling and Planning • Environmental Health and Safety (EHS) 工作概述： • 半導體封裝測試系統運轉與維護 • 生產良率管理 • 技術文件開發 • 生產調度與排程 • 環境安全防護
報名網站 Application Website	報名網站 Application Website : https://eng-web.ksu.edu.tw/DAIOISP/page/62351 https://intactbase.ksu.edu.tw/ksu/apply 
專班聯繫人 Contact	Department: Department of Electrical Engineering Name: Chen, Shin-Ju (陳信助) Professor Tel.: +886-6- 2050518 Email: sjchen@mail.ksu.edu.tw 單位：電機工程系 姓名：陳信助 教授 電話：+886-6- 2050518 Email: sjchen@mail.ksu.edu.tw 

ABOUT ChipMOS



JOIN ChipMOS CREATE THE FUTURE OF GLOBAL SEMICONDUCTORS TOGETHER

A Global Leader in Semiconductor
Packaging and Testing Services

ABOUT ChipMOS

Founded in 1997, ChipMOS is a global leader in semiconductor packaging and testing services. We provide comprehensive, reliable solutions with advanced technology and excellent quality to customers worldwide, driving innovation and empowering the semiconductor industry to move forward.



Established
1997



Global
Customers



Advanced
Technology



Leading in
Packaging &
Testing Services



OUR LOCATIONS

Taiwan Footprints

Hsinchu fab. (Headquarter)



Hukou fab.



Zhubei fab.



Tainan fabs.



Zhubei fab. 2



OUR CORE VALUES



Integrity



Innovation



Cooperation



Excellence

WHY CHOOSE ChipMOS?



Comprehensive Training

New hire training and ongoing professional development to empower your growth.



Global Work Environment

Work with diverse cultures and colleagues from around the world.



Employee Welfare & Benefits

Competitive benefits, health programs, employee care and support.



Global Semiconductor Industry

Be part of the global supply chain and create a better future together.

WORK HARD • HAVE FUN



Painting Contest



Cleanup Activity



Dragon Fruit Picking



Charity Events

CAREER OPPORTUNITIES



Equipment Engineering

- Equipment Maintenance
- Troubleshooting
- Yield Improvement



Process Engineering

- Process Improvement
- Data Analysis
- Process Optimization



Manufacturing Engineering

- New Product Introduction (NPI)
- Process Analysis
- Process Optimization



Test / Product Engineering

- Product Validation
- Anomaly Analysis
- New Product Introduction



CAREER PATH



Student



Intern



Engineer



Senior Engineer



Leader / Expert

WHY CHOOSE TAIWAN?



Global Semiconductor Leader



International Work Opportunity



Comprehensive Talent Development



Dynamic Industry & Opportunities



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Create a Brighter Future!

Notices 其他申請注意事項

- 一、報名時繳交之「畢業證書」及「歷年成績單」，除海外臺灣學校所發者外，應依教育部「大學辦理國外學歷採認辦法」規定辦理。

The diploma and transcript submitted for application review shall first be authenticated in accordance with the rules promulgated by the ROC Ministry of Education, except for diplomas and transcripts issued by overseas Taiwanese or overseas Chinese schools.

- 二、已報名或錄取之學生，如經發現申請資格不符規定或所繳交之證件有變造、偽造、假借、冒用等不實情事者，未入學者即取消錄取資格；已入學者開除學籍，亦不發給任何學歷證明；如將來在本校畢業後始發現者，除勒令繳銷其學位證書外，並公告取消其畢業資格。

Admission shall be denied and / or the student shall be dismissed from KSU after admission if there are any violations of the general academic honor code and / or in the authenticity of the applicant's documents. Those who have graduated shall have their diploma revoked

- 三、115 學年度收費標準 (115 學年標準如下)

Tuition and Miscellaneous Fee Standards for the 2026-2027 Academic Year

- (一) 學雜費收費基準 Basis for Tuition and Miscellaneous Fees

新臺幣 NTD / 每學期 Per Semester

適用學生 Applicable Program	系所 Department	學費 Tuition	雜費 Miscellaneous fee	總計 Total
學士後 Post-Baccalaureate	電機工程系 Dept. of Electrical Engineering	38,694 元	13,512 元	52,206 元

- (二) 其他收費及住宿費標準如下表(依 115 學年標準)

Please refer to the table below for other fees and accommodation fee standards.

其他費用 Other Fees	費用(新臺幣)/每學期 Fees (NTD) / Per Semester	備註 Remarks
電腦及網路通訊使用費 Computer and Internet Communication Fees	300 元	電腦及網路通訊使用費 Computer and Internet Communication Fees
電腦實習費 Computer Lab Fees	1370 元	電腦實習費 Computer Lab Fees
學生團體保險 Student Group Insurance	560 元	學生團體保險 Student Group Insurance
住宿費 Dormitory	16,100 元~23,000 元 (寒暑假住宿費另計 Accommodation fees for winter and summer vacations are calculated separately.)	套房依房型 2~3 人 Suites: 2-3 people depending on room type

註：宿舍費收費標準公告：總務處/檔案法規/宿舍費收費標準

Note: Dormitory Fee Charging Standards Announcement: General Affairs Office / Archive Regulations / Dormitory Fee Charging Standards

<https://my.ksu.edu.tw/file/web/CHT/DAGA000/de151e46-2469-465b-a2aa-fd5592d55c10.pdf>

四、115 學年度崑山科技大學新型專班學雜費收費概況表

Overview of Tuition and Fee Reductions for the 2026-2027 INTENSE PROGRAM of Kun Shan University

新臺幣 NTD/每學期 per semester

項目 Item	原訂學雜費 Original Tuition (NTD)	政府補助 Government Subsidy (NTD)	學校補助 University Subsidy (NTD)
第一學期(在校) First Semester (On Campus)	52,206	-50,000	-2,206
第二學期(在校) Second Semester (On Campus)	52,206	-50,000	-2,206
第三學期(實習) Third Semester (Internship)	52,206	-50,000	-2,206
第四學期(實習) Fourth Semester (Internship)	52,206	-50,000	-2,206
合計 Total	208,824	-200,000	-8,824

- For the second year, tuition subsidy will be awarded to the best candidates subject to performance review.



五、預估在台支付費用

Estimated expenses in Taiwan (The fee may be subject to change as appropriate.)

項目 Item	費用 Fees
6 個月外國新生醫療保險(註 Note) 6 months New International Students' Medical Insurance(NISMI) (Note) : 依據教育部規定，所有外國新生於符合臺灣全民健康保險（NHI）投保資格前，皆須投保為期六個月之外國學生醫療保險，以保障在臺期間之醫療權益與健康安全。相關保險費用由學生自行負擔。 According to the regulations of the Ministry of Education (MOE), all new international students must enroll in the International Student Medical Insurance program for the first six months before becoming eligible for Taiwan's National Health Insurance (NHI). This requirement is intended to ensure adequate medical coverage during their stay in Taiwan. Students are responsible for the insurance premium.	NTD 3,000
宿舍保證金 Dormitory deposit (It will be returned when student graduates)	NTD 3,000
宿舍房卡押金 Dormitory room card deposit (Return the deposit after receiving the student ID card)	NTD 300
健康檢查 Body Health Check-up	NTD 600 / semester
學生團體保險 Student Group Insurance	NTD 560 / semester
電腦實習費 Computer Lab Usage Fee	NTD 1,370
電腦及網路通訊使用費 Computer and Internet Usage Fee	NTD 300 / semester
外僑居留證 Alien Resident Certificate (ARC)	NTD 1,000 / year
銀行開戶 Bank Account opening (Deposit NT\$1,000, refundable after account activation)	NT\$1,000
全民健康保險 National Health Insurance (NHI) (After six months of continuous residence)	NTD 4,956 / 6 Months

- For more details, please refer to: Kun Shan University - 2027 International Industrial Talents Education Special Program (INTENSE Program) Application Information Spring Program.

更多內容，請詳閱：崑山科技大學-2027 國際產業人才教育專班(新型專班)(春季)申請入學招生簡章。